

**HOSTAFORM® S 9244 XAP®2**

POM

Celanese

Processing/Physical Characteristics	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melt volume-flow rate, MVR	1.4	cm <sup>3</sup> /10min	ISO 1133
Temperature	190	°C	-
Load	2.16	kg	-
<sup>[C]</sup> Molding shrinkage, parallel	1.7	%	ISO 294-4, 2577
<sup>[C]</sup> Molding shrinkage, normal	1.6	%	ISO 294-4, 2577

[C]: CAMPUS

Mechanical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Tensile Modulus	1450	MPa	ISO 527
<sup>[C]</sup> Yield stress	33	MPa	ISO 527
<sup>[C]</sup> Yield strain	7	%	ISO 527
<sup>[C]</sup> Nominal strain at break	>50	%	ISO 527
<sup>[C]</sup> Charpy impact strength, +23°C	N	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy impact strength, -30°C	200	kJ/m <sup>2</sup>	ISO 179/1eU
<sup>[C]</sup> Charpy notched impact strength, +23°C	18	kJ/m <sup>2</sup>	ISO 179/1eA
<sup>[C]</sup> Charpy notched impact strength, -30°C	12	kJ/m <sup>2</sup>	ISO 179/1eA

[C]: CAMPUS

Thermal properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
<sup>[C]</sup> Temp. of deflection under load, 1.80 MPa	68	°C	ISO 75-1/-2
<sup>[C]</sup> Coeff. of linear therm. expansion, parallel	130	E-6/K	ISO 11359-1/-2

[C]: CAMPUS

Electrical properties	Value	Unit	Test Standard
<b>ISO Data</b>			
<sup>[C]</sup> Relative permittivity, 100Hz	3.6	-	IEC 62631-2-1
<sup>[C]</sup> Relative permittivity, 1MHz	3.6	-	IEC 62631-2-1
<sup>[C]</sup> Dissipation factor, 100Hz	40	E-4	IEC 62631-2-1
<sup>[C]</sup> Dissipation factor, 1MHz	60	E-4	IEC 62631-2-1
<sup>[C]</sup> Volume resistivity	1E11	Ohm*m	IEC 62631-3-1
<sup>[C]</sup> Surface resistivity	1E13	Ohm	IEC 62631-3-2

[C]: CAMPUS

Other properties	Value	Unit	Test Standard
<sup>[C]</sup> Water absorption	1.2	%	Sim. to ISO 62
<sup>[C]</sup> Humidity absorption	0.2	%	Sim. to ISO 62
<sup>[C]</sup> Density	1260	kg/m <sup>3</sup>	ISO 1183

[C]: CAMPUS

**Characteristics****Processing**

Injection Molding

**Additives**

Release agent

**Delivery form**

Pellets

**Features**

Copolymer

**Other text information****Injection molding**

Above pressures, including back pressure, are given as specific or plastic pressures. The back pressure on Hostaform® and Celcon®

POM materials should be as low as possible, just enough to remove air from the pellets during feeding.